Technical Data Sheet
IBM-TDS-ER3042 V1.0

Note: The above technical parameters are onlyfor the purpose of providing product information and environmental safety information, and are not guaranteed values for product performance or quality.

****Two-Component Epoxy Adhesive**
IBM-ER3043**

Product Overview

IBM-ER3043 is a two-component epoxy adhesive designed for bonding and protection, preventing moisture or chemical corrosion. It cures at room temperature, has low viscosity, is easy to de-bubble, and is suitable for potting, structural bonding, and casting. It provides electronic components with good durability and reliability. The product contains no organic solvents and is environmentally friendly.

Product Information

Technical Requirements

Index	**Unit**	**Value**
Density @25°C	g/cm³	1.3–1.4
Mixed viscosity @25°C	mPa·s	3000–5000
Open time @25°C	≥20 min	
Surface dry time @25°C	≤4 h h	
Full cure time @25°C	≤36 min	
Cure time @80°C	<150	
Tensile strength	MPa	>50
Flexural strength	MPa	>50
Hardness (Shore D)	—	75–85
Elongation	%	2
Shear strength (SUS)	MPa	>10
85°C / 85%RH for 168h	—	No change
Thermal shock −20°C / 100°C, 1000 cycles	—	No change

Notes

This product is non-toxic after full curing. However, before curing, avoid contact with eyes and children. Ensure proper ventilation in the working environment.

Due to variations in on-site application conditions, which are beyond our control, customers should perform tests before use to confirm that our product meets their requirements.

Packaging

Bottle: 1 kg/bottle, 5 kg/ can, or customized according to customer requirements.

Storage Conditions

Store sealed in original packaging in a cool, dry, shaded place at 5–35°C. Shelf life is 12 months.

Do not pour unused adhesive back into the original container.

Keep out of reach of children.

Technical System

- Modified epoxy resin

Appearance (Uncured)

- Black liquid

Composition

- Two components

Mixing Ratio

- 5 : 1

Product Features

- Room-temperature curing
- Good toughness
- Easy de-foaming

Curing Method

- Room-temperature curing

Application

- Potting of electronic components

Storage Stability

- 12 months at 5–35°C